Special Issue

Edge Computing with Al

Message from the Guest Editors

As the computational ability of end devices grows, many of the services they provide are becoming more intelligent than ever before. For example, intelligent agriculture provides precise irrigation by sensing the environment to make a decision. Production constantly monitors the status of each piece of equipment during manufacturing to ensure high product quality. Since information is captured easily in end devices, artificial intelligence technology could be applied to predict future events or recognize critical features, thereby enabling us to tackle more everyday challenges and issues with the help of artificially intelligent end devices. In this Special Issue, we are inviting submissions on new discoveries in the applications of edge computation offering artificial intelligence services through theoretical analysis, experimental studies, and system implementations.

Guest Editors

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Dr. Neil Yuwen Yen

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Deadline for manuscript submissions

closed (10 August 2022)



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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